Silicon Mountain DRAM Building the World's Fastest PCs

David Bondurant, Retired PE Pikes Peak Life Member Affinity Group Chairman Former VP of Marketing & Applications, Enhanced Memory Systems

- Dynamic Random Access Memory (DRAM) was used on code breaking computers at Betchley Park UK during WWII using Tubes and Capacitors
- Magnetic Core Became the Main Memory for computer during 1950s and 1960s
- Dr. Robert Dennard of IBM Research patented the first semiconductor
 DRAM in 1968

June 4, 1968

R. H. DENNARD

3,387,286

FIELD-EFFECT TRANSISTOR MEMORY

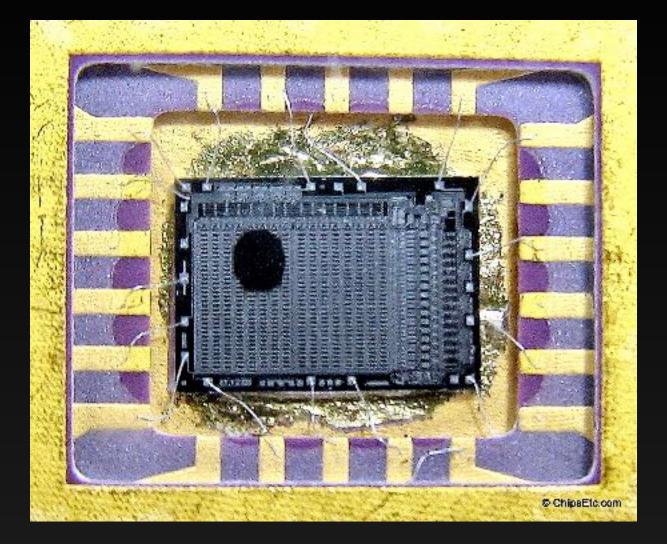
Filed July 14, 1967

FIG.1 - 20 DRIVER WORD NE WORD LINE 24-10 ---AND £ BIT КШ LINES Щ Ч 26 MPL 30 -LINE 12-26 н s m 40 ~ ÷

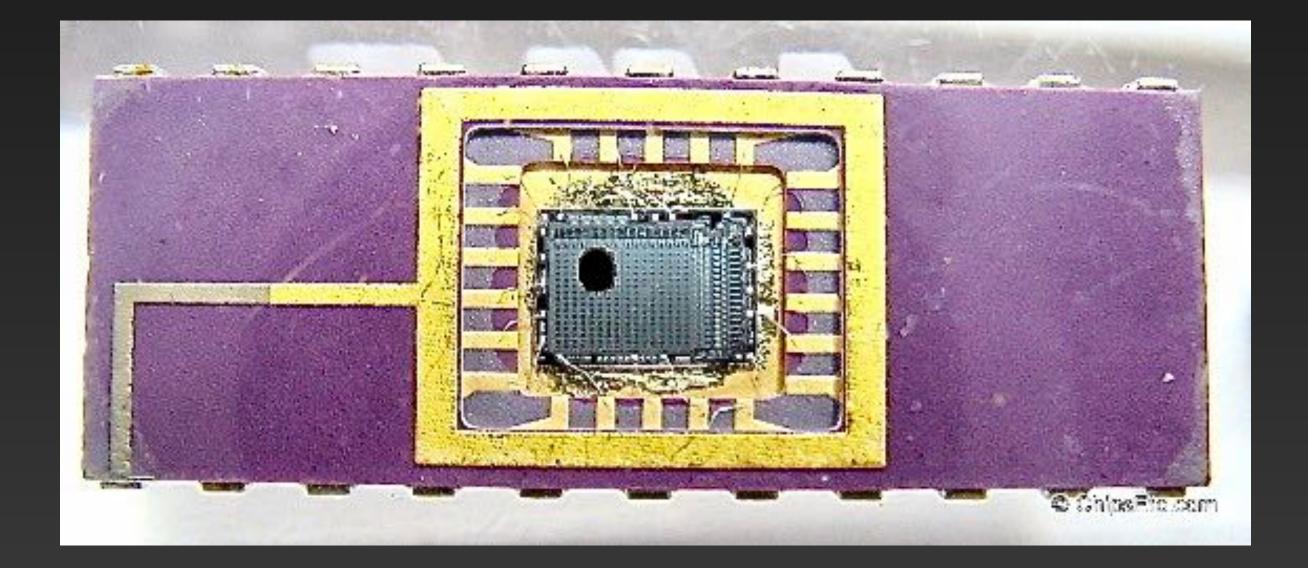
3 Sheets-Sheet 1



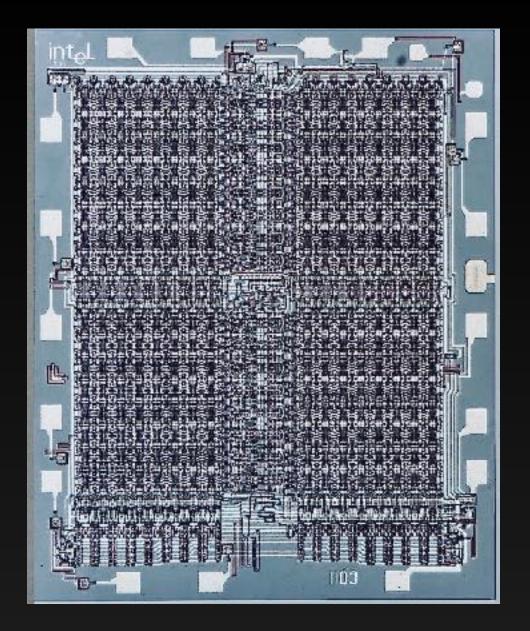
- Advanced Memory System (AMS) in Sunnyvale produced The First Monolithic 1Kbit DRAM in 1969
- AMS Founders were D.
 Berding(IBM), R. Lloyd (IBM), B.
 Dickson (Motorola), J.
 Larkin(Fairchild), and C. Fa (Collins Radio)



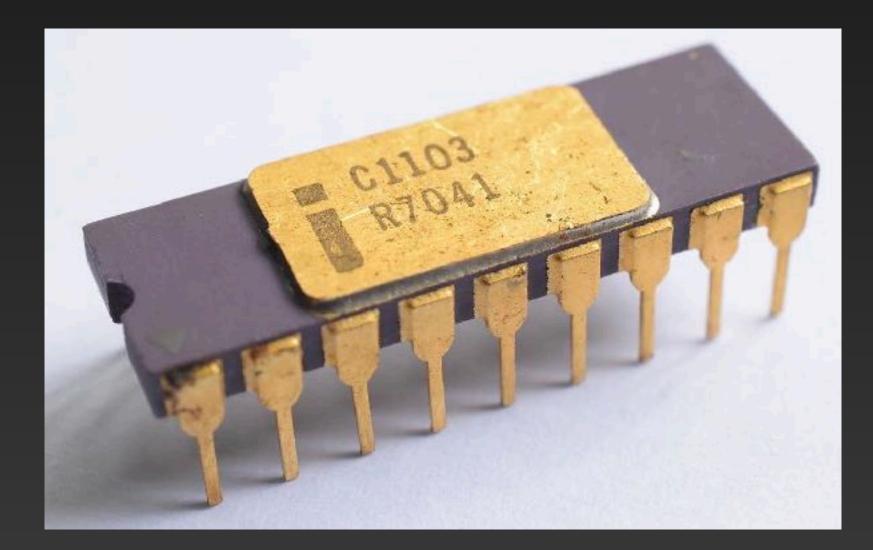
AMS 7001 1K DRAM



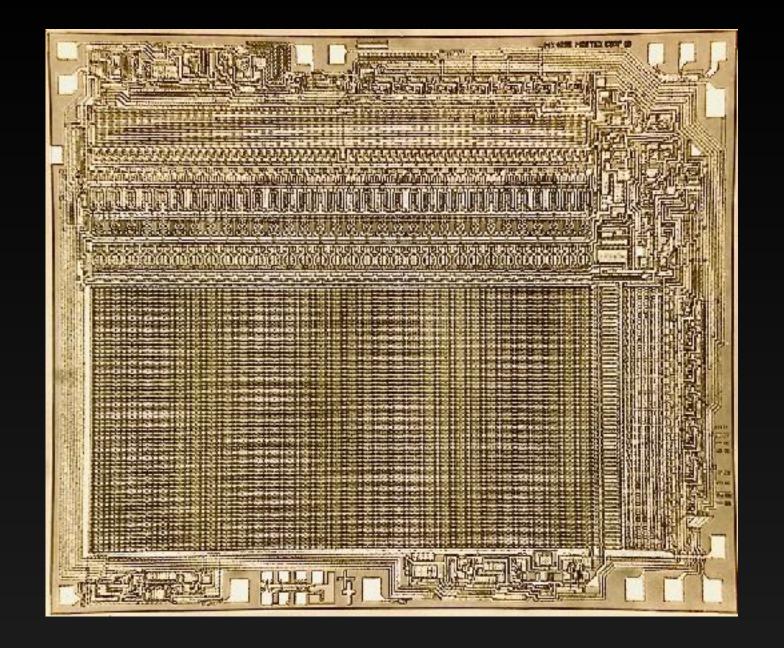
- Honeywell worked with Intel Corporation to produce the first Commercially Successful 1Kbit DRAM - 1103
- By the early 1970s, Intel's 1103 had replaced core memory
- Intel's DRAM became the world's highest volume semiconductor product



Intel 1103 1Kbit DRAM



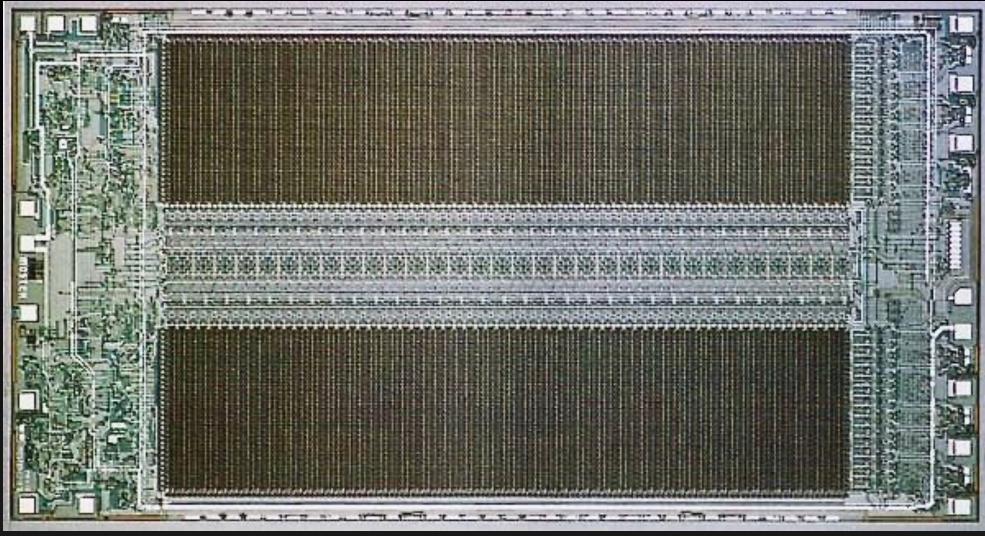
- Mostek was founded in 1969 in Carrolton, TX
- Founders were LJ Sevin, Dr. Richard Petritz from Texas
 Instruments
- Bob Proebsting was the key designer
- Mostek developed the first address multiplexed DRAM, the 4Kbit MK4096 in 1973



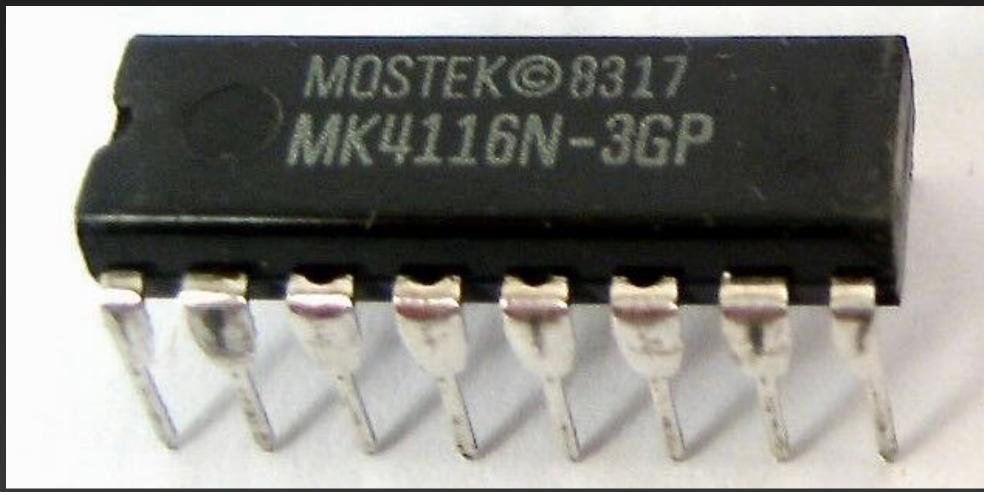
Mostek MK4096 4Kbit DRAM

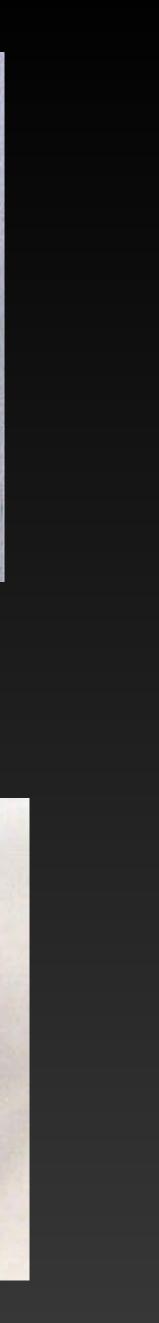


- Mostek developed a address multiplexed 16Kbit DRAM, the MK4116 by 1976
- Paul Schroeder was the key designer



Mostek MK4116 16Kbit DRAM





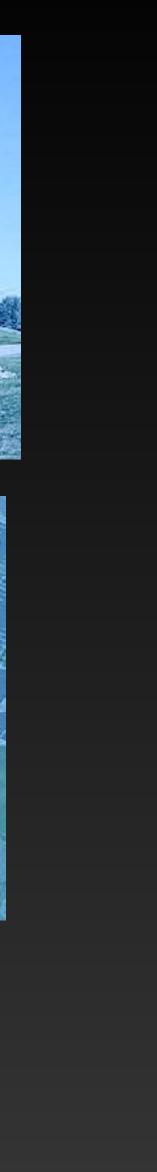
History of the DRAM NCR Microelectronics First DRAMs Built on Silicon Mountain

- NCR Corporation sent a 12 man team to open a semiconductor fab in 1975 and build a DRAM
- After attempting to develop their own, NCR Microelectronics licensed MK4116
 16K DRAM from Mostek
- Produced 16K DRAM through 1984
- NCR Fab later owned by AT&T, Symbios Logic, LSI Logic
- NCR Fab now owned by dpiX, a leading X-ray Sensor Company since 2011





Former NCR Microelectronics Fab Now dpiX at 1635 Aeroplaza Drive Colorado Springs, CO



- By 1976, Mostek held 85% market share in DRAM and was ready to expand to a new facility
- By the late 1970s, Japanese companies were entering the DRAM market. Dark clouds were gathering.
- Mostek would be late to market with their 64Kbit DRAM

Table 6.3	The changing	patterns of	f market	leadership	in DRAMs
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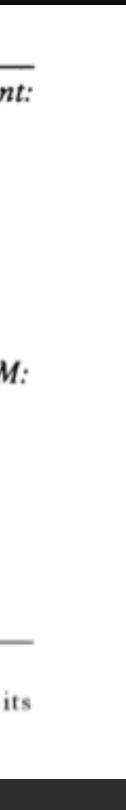
Memory introduction dates and the initial leading four firms in each market segment:

Date	1974	1976	1979	1979	1982	1985
Leading firms	Intel TI Mostek NEC	Mostek Intel NEC Fujitsu	Intel Hitachi Fujitsu Motorola	Motorola Fujitsu Hitachi TI	Hitachi Fujitsu NEC AT&T	Toshiba Hitachi AT&T NEC

Number of major suppliers in world market three years after introduction of DRAM:

<i>Date</i> DRAM size	<i>1974</i> 4K	<i>1976</i> 16K*	<i>1979</i> 16K	<i>1979</i> 64K	<i>1982</i> 256K	<i>1985</i> 1МЬ
Japanese US	1	4	2	6	6	7
	8	8	5	3	5	4
European	1	2	0	0	0	1
Korean	0	0	0	0	0	1

Source: Based on data from Dataquest Europe, Denham UK Note: One of the four US producers of the 1Mb DRAM within three years of its introduction was the previously captive producer AT&T



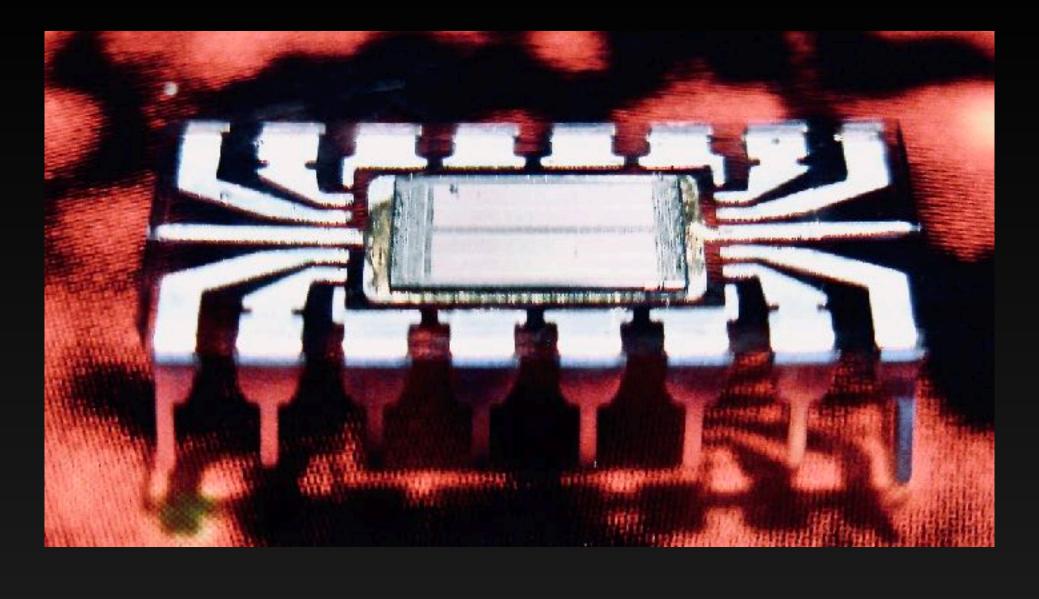
- Mostek would build a major DRAM factory on Garden of Gods Road in Colorado Springs by early 1980s.
- This facility would build 64Kbit and 256Kbit DRAM
- This facility would later become UTMC, Rockwell International, and Intel Fabs



a Major Facility for Intel

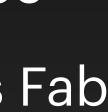


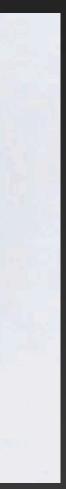
- Mostek would launch the 64Kbit MK4564 from the Colorado Springs fab
- By 1981, Fujitsu, Hitachi, Mitsubishi, NEC, and Oki had entered the 64K DRAM market
- DRAM Demand would peak in 1984
- During a market downturn in 1985, demand would decrease and increasing competition would drive Mostek to major osses
- Intel & TI would leave the DRAM Market in 1985, AT&T would leave the market in 1987
- Mostek would be sold to United Technologies. The DRAM business would be sold to SGS-ATES which would later become STMicroelectronics
- The United Technologies Microelectronic Center (UTMC) would focus of military grade memory and microprocessors occupying a part of the former Mostek Fab



Mostek MK4564 64Kbit DRAM would be the primary product of Colorado Springs Fab



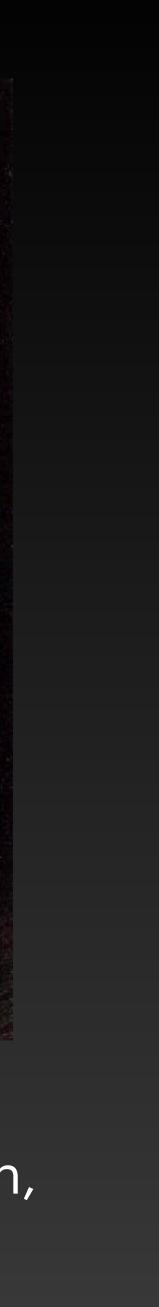




- 1979 Inmos Corporation was formed with support from the British Enterprise Board
- Founders were Paul Schroeder, lan Barron, and Dr. Richard Petritz
- The Inmos DRAM Design & Manufacturing facility was located in Colorado Springs, CO

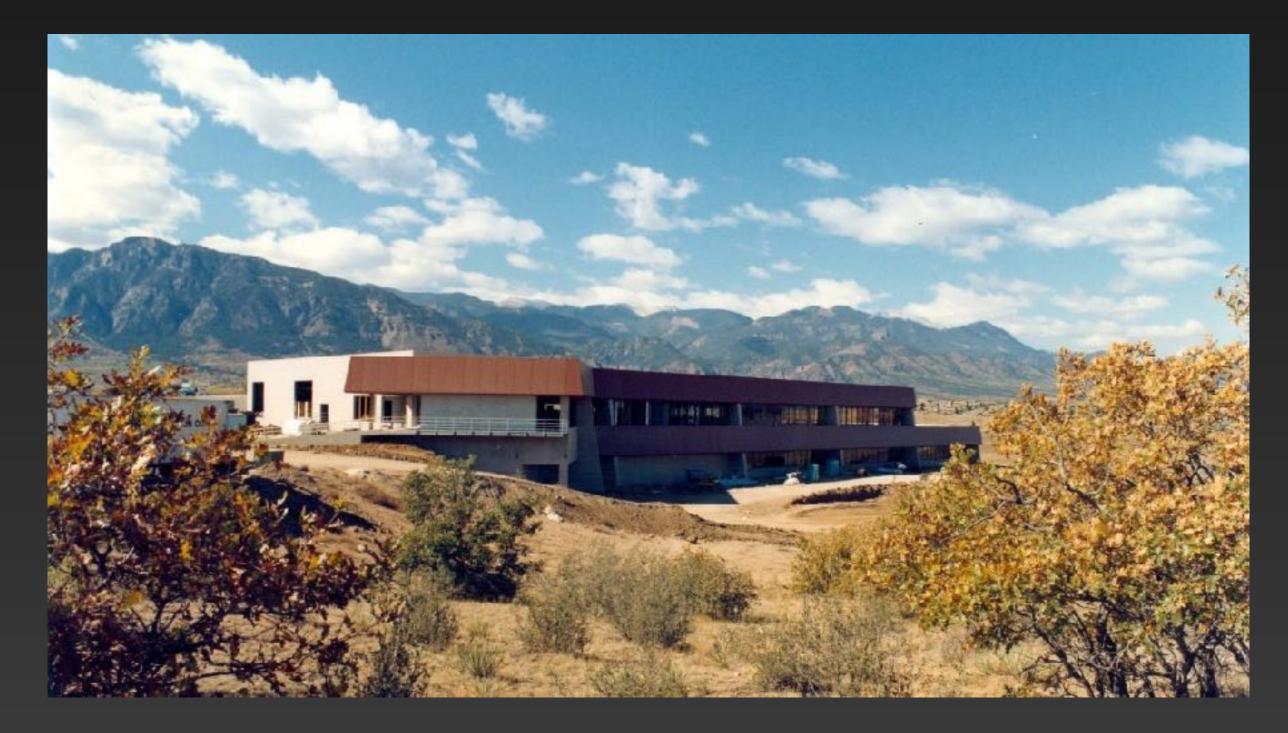


Founders - Paul Schroeder, Ian Barron, and Dr. Richard Petritz



- US Facility was Located on Cheyenne Mountain next to the Honeywell Semiconductor Facility
- Inmos would develop SRAM, DRAM, and Transputers
- It would manufacture & sell 64Kbit DRAM built in Colorado Springs
- Sold to Thorn EMI by the British Government in 1984
- It would reach \$68 Million in Revenue by 1986
- In 1986, Inmos designed a high performance 256K DRAM for NMB Semiconductor in Tateyama, Japan
- The 256K DRAM was the world's first CMOS DRAM product and fastest with 60 ns cycle time. The rest of the DRAM industry would switch to CMOS at 1Mbit.





History of the DRAM Ramtron, Non-Volatile DRAM

- Ramtron Australia Ltd. was founded in 1984 in Colorado Springs by George Rohrer, Dr. Carlos Araujo, and Larry McMillan
- Ross Lyndon-James would be the first CEO
- Ramtron developed Ferroelectric RAM technology emerging from the UCCS Microelectronics Laboratory



Ramtron HQ in Colorado Springs

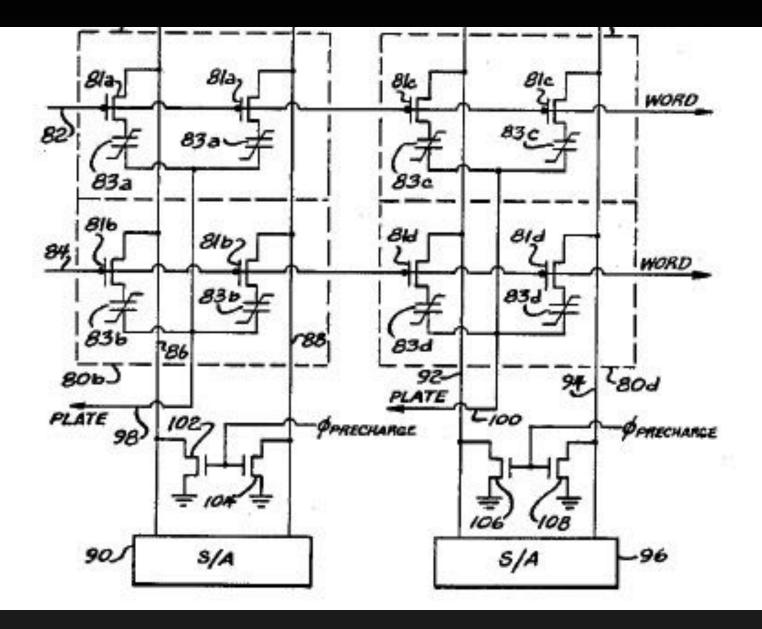


George Rohrer, Larry McMillan, Ross Lyndon-James on University of Colorado-Colorado Springs Campus

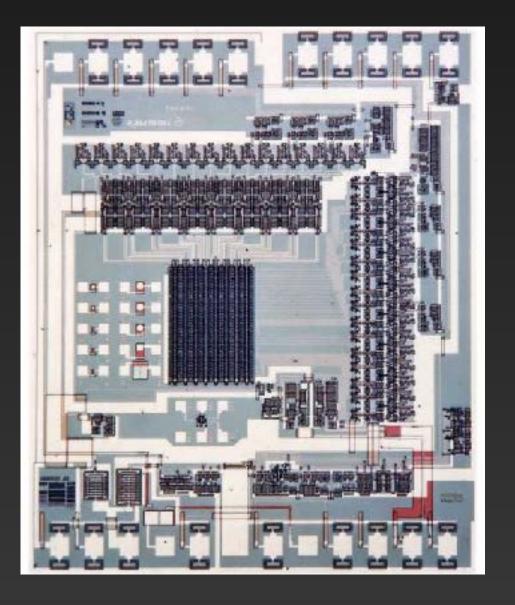


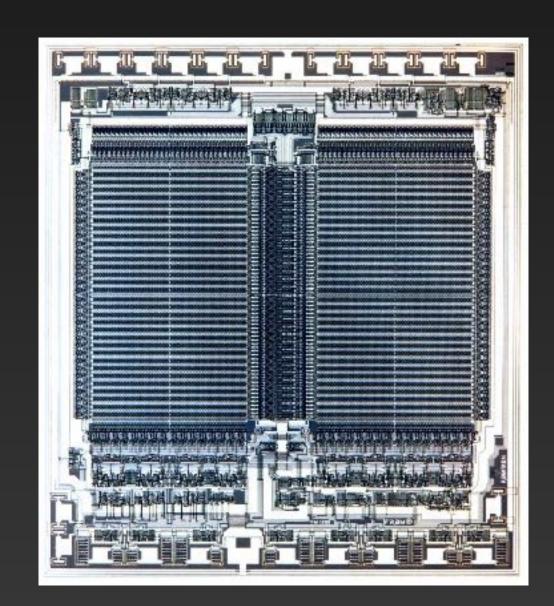
History of the DRAM Ramtron, Non-Volatile DRAM

- In 1986, Ramtron hired key personnel from Inmos.
 - Dr. Fred Gnadinger as VP of R&D
 - Sheff Eaton and his team of DRAM designers to develop FRAM Memory
- Sheff Eaton patented the first 1T-1C ferroelectric RAM, a non-volatile DRAM
- By 1988, Ramtron demonstrated the first 256-bit Ferroelectric RAM
- The Inmos DRAM team developed the first production 4K FRAM in 1989.



Ramtron Patented 1T-1C FRAM Cell





FMx8101 256-bit 2T2C FRAM

FM1208 4K 2T2C FRAM

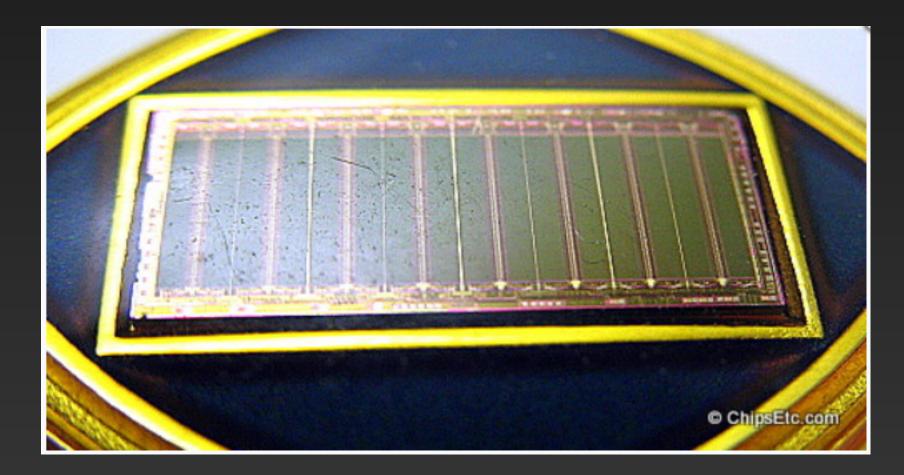


History of the DRAM United Memories Inc.

- In 1990, Ramtron formed a joint venture company called United Memories with NMB Semiconductor (Tateyama, Japan)
- Ramtron DRAM Design Team Moved to
 United Memories
- NMBS Built a \$300M DRAM Fab in Japan
- United Memories designed 1Mbit & 4Mbit
 Fast CMOS DRAM Products for NMBS
- These DRAMs were the Fastest DRAMs Available at 60 ns Cycle Time.
- Ramtron Received Design Fees and Royalties From NMBS DRAM Sales



Bob Gower, CEO of United Memories Sheff Eaton becomes President



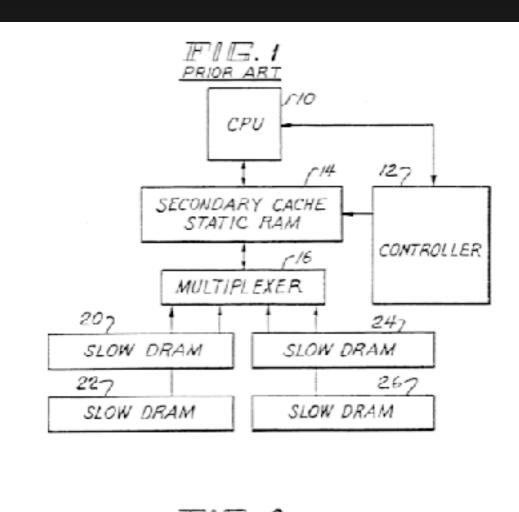
Ramtron-NMBS 4Mbit DRAM (60 ns) World's Fastest DRAM

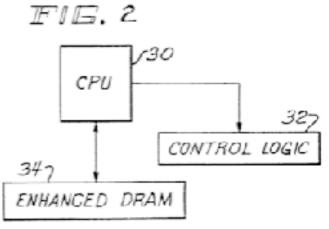
History of the DRAM **Ramtron Enhanced DRAM (EDRAM)**

- In 1990, Ramtron decided to develop a unique DRAM product based on NMBS fast DRAM technology
- Cheetah International in Colorado Springs was building fast PCs based on available DRAMs
- Ramtron, United Memories, and Cheetah International defined the Enhanced DRAM, a Cached DRAM
- EDRAM Targeted the Emerging High-end PC Market
- United Memories modified NMBS 4Mbit DRAM with integrated SRAM cache row registers
- NMBS prototyped the 4Mb EDRAM by 1991
- The EDRAM Became the Fastest 4Mbit DRAM Product on the market by 1992

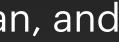


Ron Sartore, President of Cheetah International





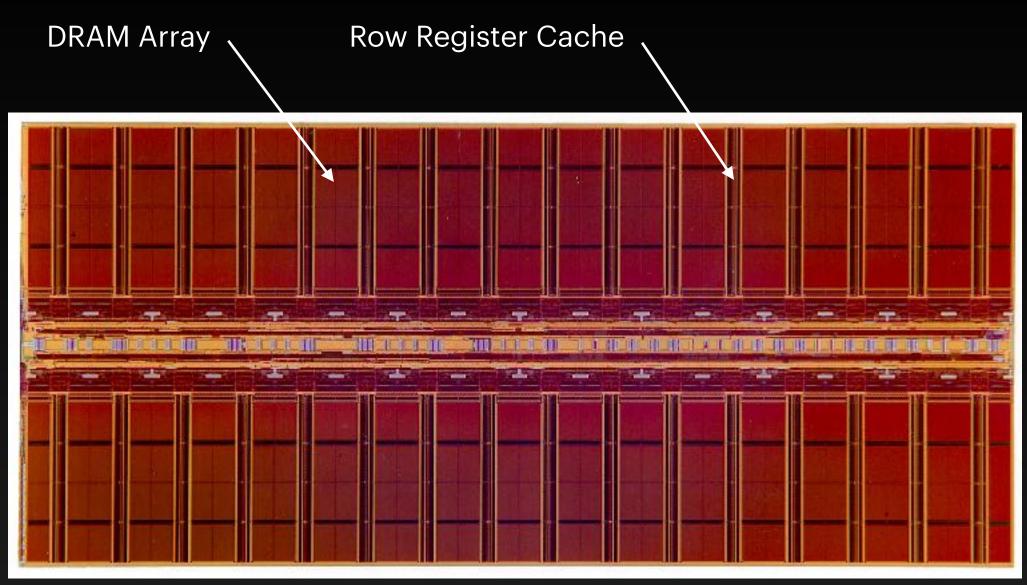
Patent #6,347,357 Enhanced DRAM with Embedded Registers Sartore, Mobley, Carrigan, and Jones 1/22/92



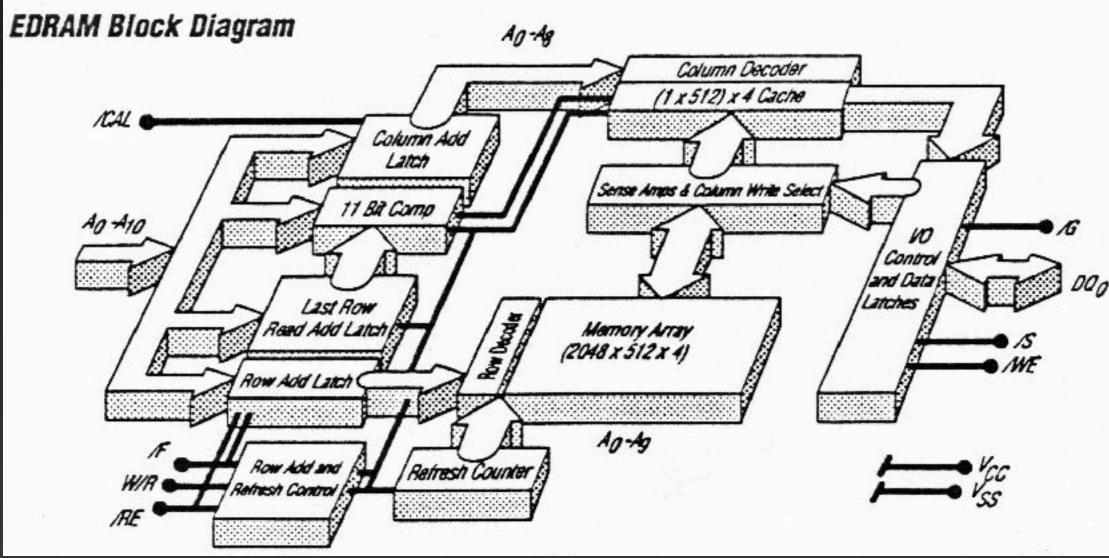
History of the DRAM

Ramtron Enhanced DRAM (EDRAM)

- Ramtron Enhanced DRAM (EDRAM) integrated a 2Kbit
 SRAM Row Cache into the NMBS Fast DRAM Core
- While Pin Compatible with Standard 4Mbit Asynchronous DRAM, EDRAM could randomly read or write data within a row in 15ns
- If an access to EDRAM missed the cached Row, read access time was 35 ns
- Unlike Standard DRAM, EDRAM could be refreshed at the same time data was read or written to the Row Cache
- This architecture would allow data read & write operations with zero wait states like SRAM cache
- EDRAM was introduced in January 1992, was sampled in July 1992, and entered production in January 1993
- EDRAM would be produced for over 8-years



Enhanced DRAM Die

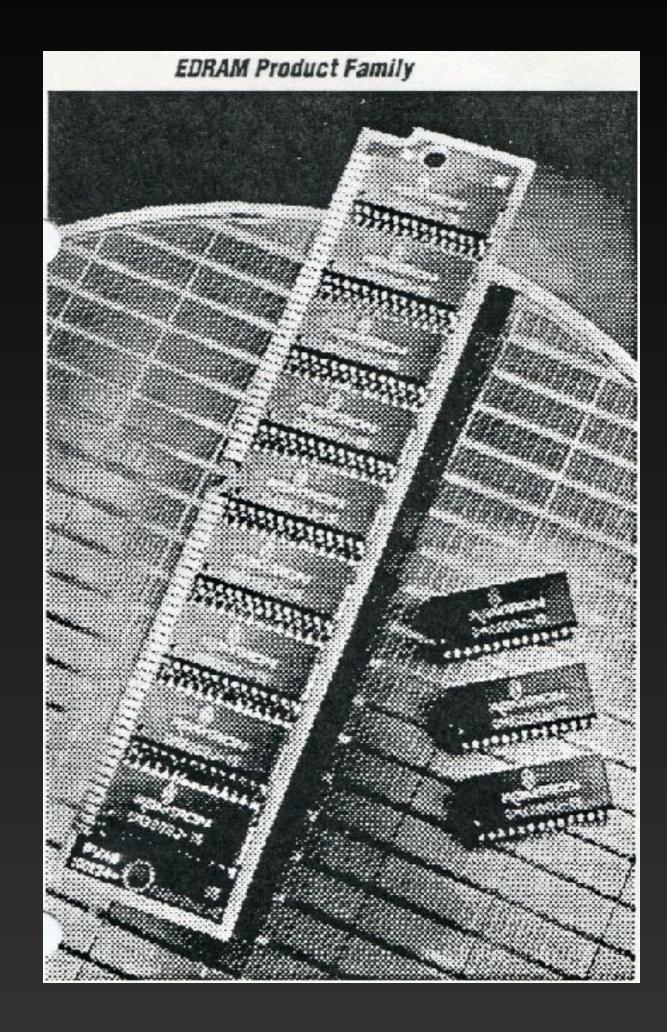




History of the DRAM Ramtron Enhanced DRAM (EDRAM)

DRAM Performance Comparison					
Mode	15ns EDRAM	70ns DRAM	Comment		
Random Cycle Time	65ns	130ns	2X Faster		
Random Access Time	35ns	70ns	2X Faster		
Page Read Cycle Time	15ns	40ns	2.7X Faster		
Page Access Time	15ns	35ns	2.3X Faster		
Page Miss Access Time	35ns	130ns	3.7X Faster		
First Write-In Page	15ns	40ns	2.7X Faster		
Page Write Cycle Time	15ns	40ns	2.7X Faster		

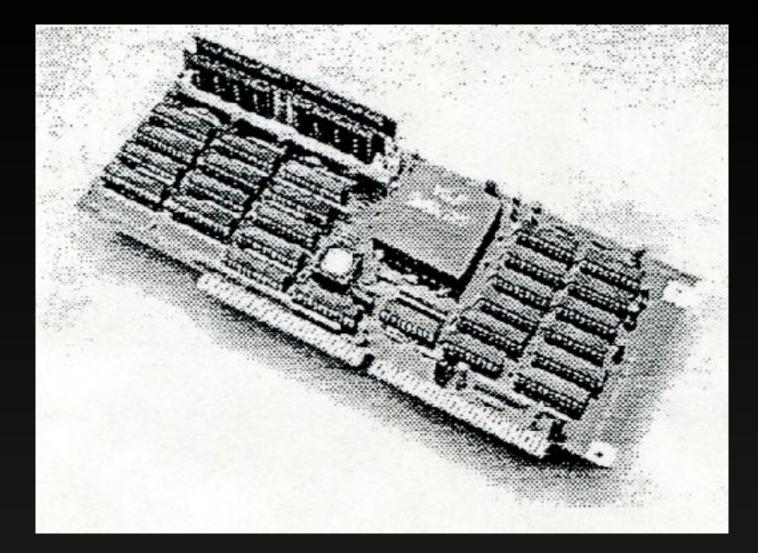
EDRAM was more than 2X Faster Standard DRAM



Original Product Picture 1992

History of the DRAM The World's Fastest PCs

- EDRAM was first disclosed publicly at the First Silicon Valley PC Conference in 1991
 - Ron Sartore documented his modified Cheetah Gold 486-33
 System with EDRAM
 - "New Generation of Fast, Enhanced DRAMs Replace SRAM Cache in High-End PC Workstations"
 - He found EDRAM faster than several Fast Memory Alternatives
- Ramtron Approached Intel For Support In Developing an Intel Motherboard
 - Ed Solari of Intel Hillsboro provided an existing Intel Motherboard Design and Recommended Dr. Design, an Intel Contractor to support the Ramtron Design
 - First Ramtron PC Design was disclosed at the Third Silicon Valley PC Conference in 1993
 - "Cacheless Fast DRAM Memory System Improves 486DX2-66 System Performance"
 - System Demonstrated Clear Advantage over SRAM Cache in Unix Benchmarks and Basic Memory Tests



Ramtron 486DX2-66 with EDRAM

E JANK	PC Labs V7.0		' ang sa
	Processor	新作用	
EDRAM	(2)-	16626.35	
256K Cache	1	16394.00	1.4%
DRAM	10244.00		62.3%
	Memory		
EDRAM		9440.00	
256K Cache	5599.00		68.6%
DRAM	5905,00		36.7%

Byte	: OOS V2.2 CPU Index	
li · · ·	2.13	
	1.69	25.0%
	1.33	60.2%
	Byte	Eyte DOS V2.2 CPU Index 2.13 1.691

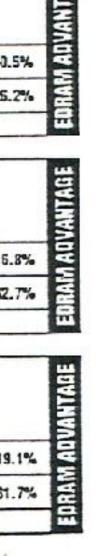
	Norton Si VG.Ot CPU Index	
EDRAM	90.00	
256K Cache	90.30	-0.5%
DRAM	56,901	35.9%

	Wintach V1.2	13 au
EDRAM	17.53	
256K Cache	17.52	-
DRAM	13.89	2

	SPECINT92 (50MHz)		
EDRAM]	21.90	
256X Cache	2	0.50	1
DRAM	16.50		3

	SPECFP92 (50MHz)	4.95
EDRAM	13.70	
256K Cache	11.50	19
DRAM	10.40	31

Benchmark Results

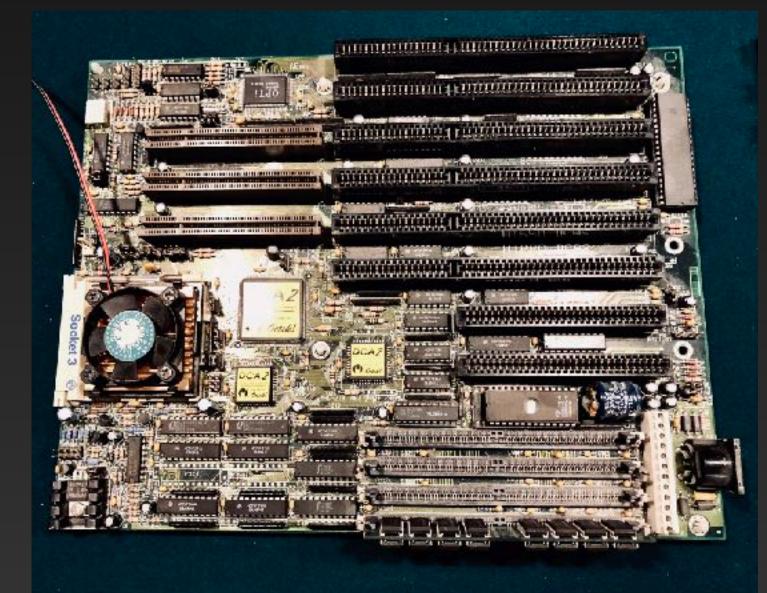


History of the DRAM The World's Fastest PCs

- Based Upon It's Work with Intel, Ramtron Developed a Custom Chipset Based Upon Intel FlexLogic FPGA
 - Won First Taiwan Motherboard Design with Digicom
 - It was first demonstrated at Comdex 1993
 - By July 1994, Softwin Reports tested Digicom System vs. Dell OptiPlex with 128KB SRAM cache vs. 66MHz Pentium with 512KB SRAM Cache
 - Softwin Found Digicom 486DX2-66 approached Pentium System performance
- Ramtron worked with Ocean Information Systems (Hong Kong) who developed their own optimized chipset in 1994
 - Softwin Reports awarded Ocean DCA2 their Top Gun Award as the fastest 486DX4-100 System tested and faster than a Pentium 100MHz system



Digicom 486DX2-66 Motherboard with EDRAM

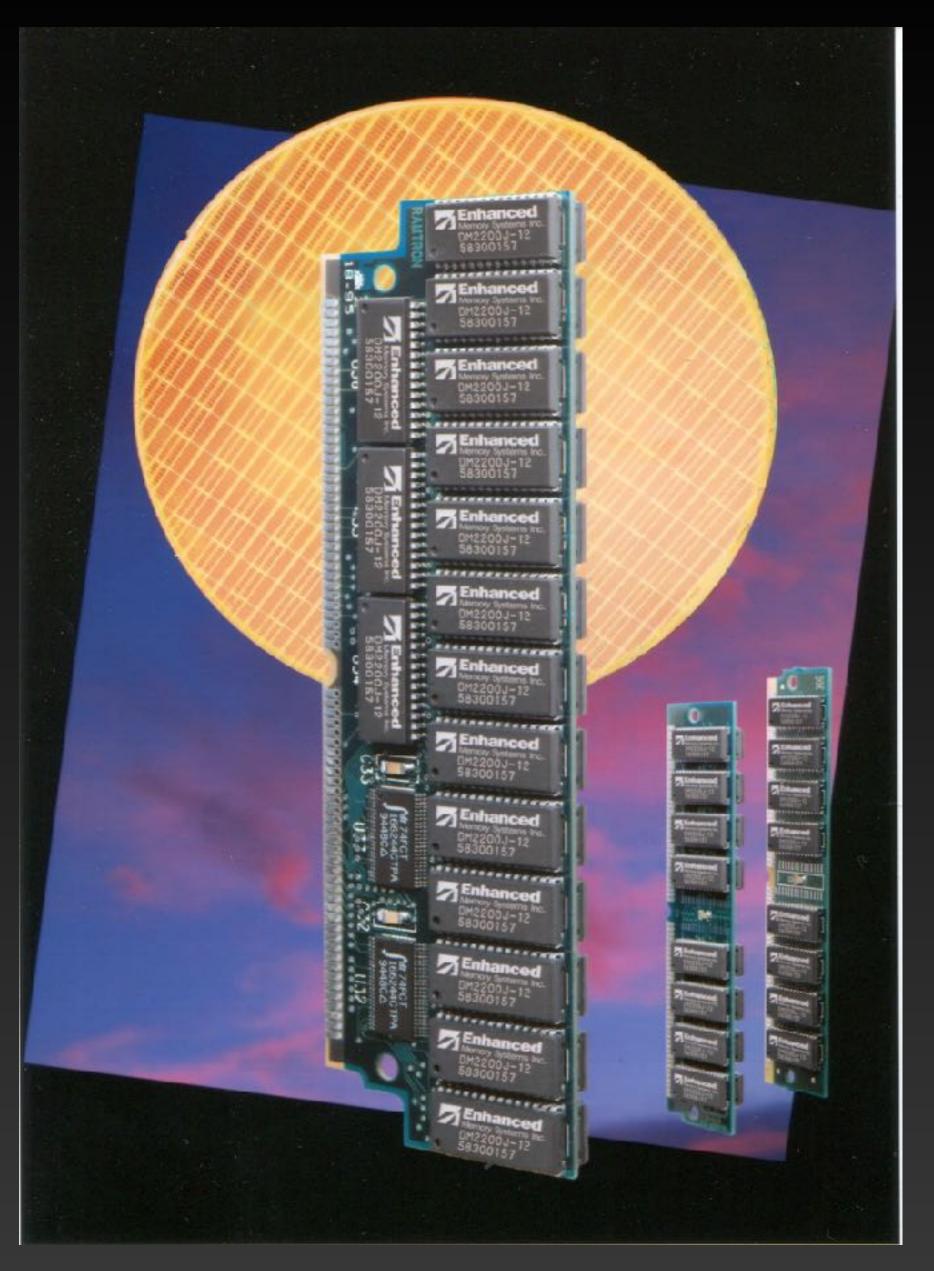


Ocean Information Systems 486DX4-100 DCA2 Motherboard With EDRAM



History of the DRAM Enhanced Memory Systems

- In 1995, Ocean would be ready to place \$100M order for EDRAM
- Ramtron's Major Investor, Oren Benton was going Bankrupt
- Ramtron could not fund the work in process (WIP) to take the order
- Based upon test results from EDRAM Motherboards, Ramtron would negotiate a second sourcing agreement with IBM
- Ramtron would spin-out EDRAM Business as separate subsidiary, Enhanced Memory Systems
- Enhanced Memory Systems would refocus business on SRAM Replacement and reach \$16M Revenue in 1986



Enhanced Memory Systems Product Picture 1995

History of the DRAM Enhanced Memory ESDRAM

- Enhanced Memory would produce 4Mb
 EDRAM at IBM's Factory in Essonnes, France
- Enhanced Memory and IBM would invent and patent the Enhanced Synchronous DRAM (ESDRAM)
- A 16Mb ESDRAM product family would be built at IBM but would be late to market and not a factor in the PC main memory market
- PC focus would shift to Licensing EDRAM Technology to Mainstream DRAM Manufacturers
- In 1998, ESDRAM and DDR ESDRAM would become JEDEC Superset DRAM Standards

United States Patent [19]

Miller et al.

- [54] CACHED SYNCHRONOUS DRAM ARCHITECTURE ALLOWING CONCURRENT DRAM OPERATIONS
- [75] Inventors: Christopher Paul Miller. Underhill; Jim Lewis Rogers. Miltou; Steven William Tomashot, Williston, all of Vt.
- [73] Assignee: International Business Machines Corporation, Armonk, N.Y.
- [21] Appl No.: 731,790
- [22] Filed: Oct. 18, 1996

- 711/119, 117, 168
- [56] References Cited

U.S. PATENT DOCUMENTS

Primary Examiner-Eddic P. Chan Assistant Examiner-Hiep T. Nguyen Attorney, Ageni, or Firm-Robert A. Walsh

[45] Date of Patent: Jul. 28, 1998

5,787,457

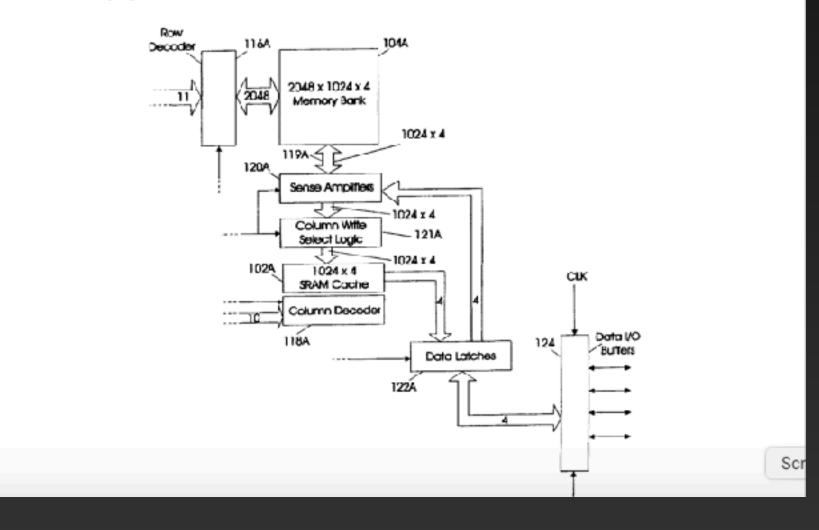
ABSTRACT

[11] Patent Number:

[57]

A cached synchronous dynamic random access memory (cached SDRAM) device having a multi-bank architecture includes a synchronous dynamic random access memory (SDRAM) bank including a row decoder coupled to a memory bank array for selecting a row of data in the memory bank array, sense amplifiers coupled to the memory bank array via bit lines for latching the row of data selected by the row decoder, and a synchronous column select means for selecting a desired column of the row of data. A randomly addressable row register stores a row of data latched by the sense amplifiers. A select logic gating means. disposed between the sense amplifiers and the row register. selectively gates the row of data present on the bit lines to the row register in accordance to particular synchronous memory operations of the cached SDRAM being performed. Data to be input into the cached SDRAM during a Write operation is received by the sense amplifiers and written into the memory bank array. Data to be output from the cached SDRAM during a Read command is read out only from the row register, the row of data contained in the row register first having been read from the memory bank array to the sense amplifiers and then selectively gated to the row register in accordance with the particular synchronous memory operations.

9 Claims, 13 Drawing Sheets



ESDRAM Patent #5,787,457 Later Assigned to Bondurant, Jones, and Mobley

History of the DRAM Enhanced Memory HSDRAM

- Enhanced Memory would negotiate a foundry agreement with Infineon (Dresden, Germany) and design a 64Mbit ESDRAM but it would not make it to the market
- To recapture the high performance PC Market, Enhanced Memory would procure a high speed version of a conventional DRAM with PowerChip Semiconductor (Taiwan)
- The Enhanced HSDRAM would achieve 2:2:2 latency at 133 MHz and could be overclocked to up to 166 MHz

Operating Frequency	CAS Latency	64MB DIMMs Installed	128MB DIMMs Installed
150	3	2	2
143	3	2	2
138	3	3	2
133	3	4	3
133	2	2	2
125	2	3	2
112	2	4	4
100	2	4	4



Preliminary Data Sheet

Features

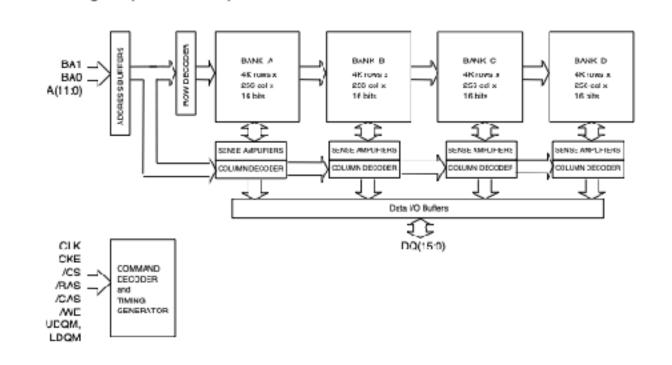
- JEDEC Standard PC-133 SDRAM
- Fast 4.5 ns Clock Access Time
- Low Latency Operation (3:2:2 @ 150 MHz)
- CAS Latency = 3
- RAS to CAS Delay = 2
- Precharge Delay = 2
- Fast Random Access Time (31.2 ns)
- Fast Random Cycle time (53.3 ns)
- Programmable Burst length (1, 2, 4, 8, full page)
- Programmable CAS Latercy (2, 3)
- Low Power suspend, Self Refresh, and Power Down Modes Supported
- Down Modes Suppo
- 4K Refresh / 64 ms
- Single 3.3V ± 0.3V Power Supply
- 54-pin TSOP-II (0.8mm pin pitch)

Block Diagram (4Mx16 shown)

64Mbit – High Speed SDRAM (150 MHz) 8Mx8, 4Mx16 HSDRAM

Description

The Enhanced Memory Systems SM3603 and SM3604 High-Speed SDRAM (HSDRAM) devices are high performance versions of the proposed JEDEC PC-133 SDRAM. While compatible with standard SDRAM, they provide the faster clock access time (4.5 ns), shorter random access latency (31.2 ns), and fast bank cycle time (53.3 ns) needed to improve system stability, capacity, and performance in systems operating at 150 MHz bus speed. The HSDRAM is ideal for any high performance system including PCs, workstations, servers, communications switches, DSP systems, 3-D graphics, and embedded computers.



Enhanced Memory Systems Inc., 1850 Ramitron Dr., Colo Spgs, CO 80821 PhONE: (809) 545-DHAM; PAX: (719) 455-9095; http://www.ecran.com Revision: 1, C 1999 Enhanced Menory Systems. All rightsreserved. The information contained herein is subject to change without notice.

Page 1 of 9



Enhanced Memory Systems HSDRAM Product Picture 1999





History of the DRAM Mushkin Enhanced Memory

- Enhanced Memory Systems would work with Mushkin, a Denver-based memory module supplier to gaming & overclocker PC markets to build HSDRAM module products
- Ramtron would buy Mushkin and make it a whollyowned subsidiary
- The Mushkin Enhanced PC150 HSDRAM Module would achieve 2:2:2 latency at 133 MHz and could be overclocked to up to 166 MHz
- Mushkin would develop a unique DRAM heatsink design to allow stable operation at high clock rates
- Mushkin continues as a leading e-commerce supplier of memory modules, SSD modules, and other electronic components today

EQUAL PARTS PROGRESSIVE AND PURIST. FAST. RELIABLE. STYLISH.

Mushkin Silverline DDR4 memory modules are designed o exceed industry standards and guarantee maximum compatibility with virtually all Intel and AMD powered PCs.

Cut from aircraft-grade aluminum for faster heat dissipation, the Silverline's newly redesigned heatsink is a model of durability. This industrial, yet elegantly crafted heatsink takes Mushkin's world renowned Silverline product line to a new level.

An ideal solution for DIY'ers, gamers and system builders who know they want high performance, but also need to keep costs under control, the heatsink's diamond cut design will definitely turn heads.





Mushkin Enhanced PC150 HSDRAM Product Picture 1999

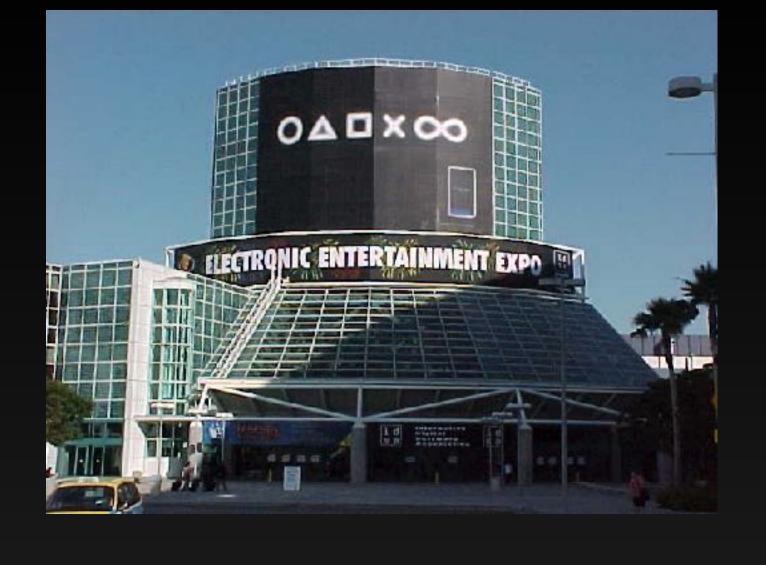
History of the DRAM

Mushkin at E3, The World's Fastest Athlon 700

- Mushkin would exhibit at Electronic Entertainment Expo in Los Angeles in May 2000
- Mushkin and Enhanced Memory would develop "Freak Machine", the world's fastest Athlon 700 PC overclocked to 964 MHz



HSDRAM delivered in unique bubble pack



What is it about this memory that makes it so good? Could it be the fact that it's running at a low-latency 150 MHz, compared to 100 or 133 MHz that other memory DIMMs are known for? Maybe it's the lightning fast 4.5 ns clock access time that makes it so great. Whatever it is, you can rest assured that this is some of the best memory I have ever used, and will definitely go back to them should I wish to upgrade.

Mushkin was on display at E3 last May, where they displayed what they called their "Freak Machine." With this new memory, the Freak was running an Athlon-based PC at a previously unheard of 964 MHz. Benchmarks of Quake 3, Unreal Tournament, and Incoming all had frame rates in the triple digits! Now I know my Athlon 700 will not come anywhere near these levels, but I have noticed a considerable speed boost in my games. Unreal Tournament now runs near constant at 60 at 1024×768 resolution, and Quake 3 does the same at 800×600.

A strip of 128 MB PC150 memory runs for \$119 (as of writing this review), and it's definitely worth it. They can be found at www.mushkin.com.

Mushkin Freak Machine Shown at E3, May 2000 The Fastest Athlon 700 Overclocked to 964 MHz



History of the DRAM

The World's Highest Density SRAMs

- By 1998, Enhanced Memory Systems recognized they could not keep pace with commodity DRAM density
- Focus changed to creating 1 Transistor SRAM Products that were 4X higher density than SRAM
- Enhanced Memory negotiated a foundry agreement with Infineon (Dresden, Germany) - Infineon would take 30% Ownership Position in Ramtron/Enhanced Memory
- Enhanced Memory patented an Enhanced SRAM (ESRAM) version of ZBT SRAM
- Enhanced Memory partnered with Cypress Semiconductor (the Largest SRAM Supplier) to develop a 72-Mbit ZBT ESRAM
- Enhanced Memory Systems partnered with Hewlett Packard to develop a 72-Mbit DDR ESRAM for L3 Cache Application

United States Patent [19]

Bondurant et al.

[54] ENHANCED BUS TURNAROUND INTEGRATED CIRCUIT DYNAMIC RANDOM ACCESS MEMORY DEVICE

- [75] Inventors: David Bondurant; David Fisch, both of Colorado Springs; Bruce Grieshaber, Colorado Spring; Kenneth Mobley; Michael Peters, both of Colorado Springs, all of Colo.
- [73] Assignce: Enhanced Memory Systems, Inc., Colorado Springs, Colo.
- [21] Appl. No.: 09/515,007
- [22] Filed: Feb. 29, 2000
- [58] Field of Search 365/49, 203, 222

[56] References Cited

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[11]	Patent Number:	6,151,236
[45]	Date of Patent:	Nov. 21, 2000

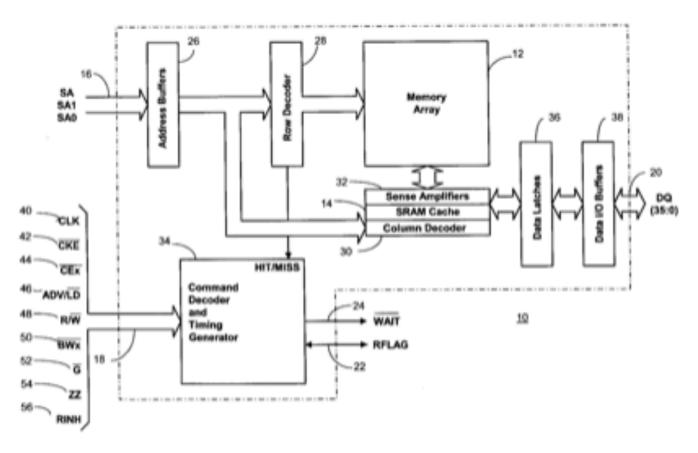
Primary Examiner-Son T. Dinh

Attorney, Agent, or Firm-William J. Kubida, Esq.; Carol W. Burton, Esq.; Hogan & Hartson LLP

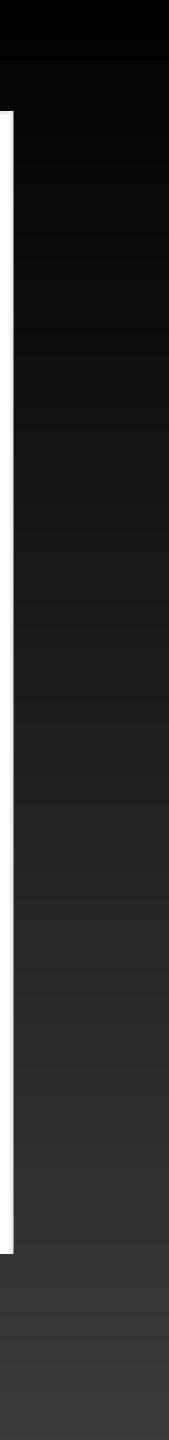
[57] ABSTRACT

An enhanced bus turnaround integrated circuit dynamic random access memory ("DRAM") device of particular utility in providing maximum DRAM performance while concomitantly affording a device with may be readily integrated into systems designed to use zero bus turnaround ("ZBT"), or pipeline burst static random access memory ("SRAM") devices. The enhanced bus turnaround DRAM device of the present invention provides much of the same benefits of a conventional ZBT SRAM device with a similar pin-out, timing and function set while also providing improvements in device density, power consumption and cost approaching that of straight DRAM memory. Through the provision of a "Wait" pin, the enhanced bus turnaround device of the present invention can signal the system memory controller when additional wait states must be added yet still provide virtually identical data access time performance to that of ZBT SRAM for all Read and Write operations with a burst length of four or greater. Use of master/slave and inhibit pins.

7 Claims, 8 Drawing Sheets



Enhanced Memory ZBT ESRAM Patent - 2000



One Transistor ESRAM Products

NoBL Burst SRAM

- 2Mx36
- 100, 133, 166 MHz Clock Rates
- NoBL Pin Compatible
- 100-Pin TQFP, 119-Pin PBGA
- +3.3 & 2.5 Volt I/O and Power Supply

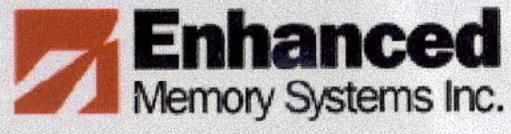


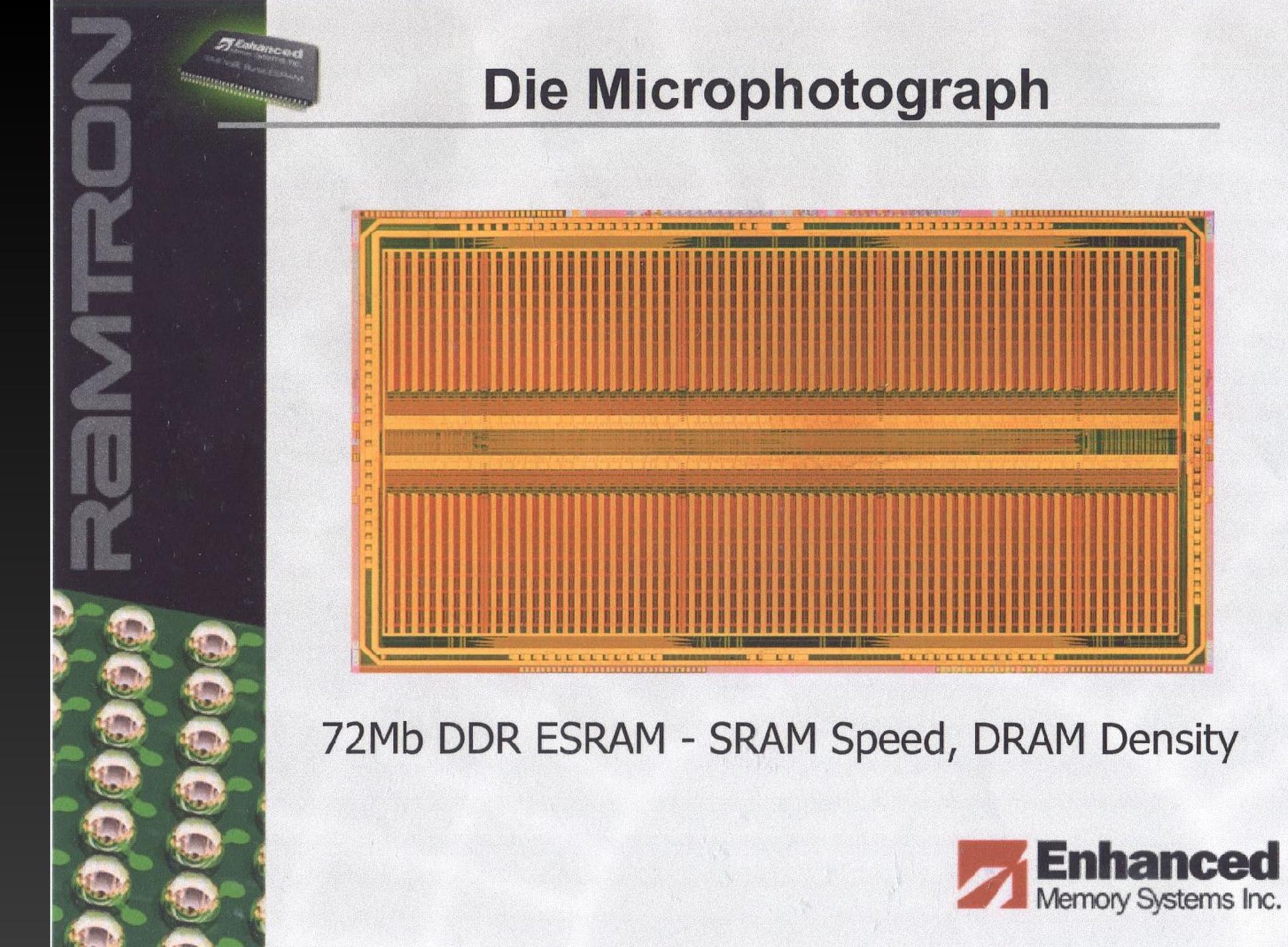
DDR SRAM

PBGA Power Supply

- 2Mx36
- 300 MHz Clock Rates
- 2.4GB/Second Bandwidth
- 209-Pin PBGA
- +2.5 Volt Power Supply
- +1.2 Volt HSTL I/O





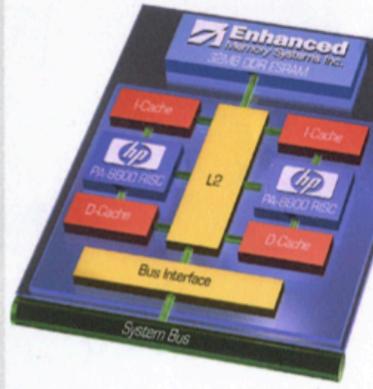


History of the DRAM

The World's Highest Density SRAMs

- Enhanced Memory and Cypress would ship 72Mbit ESRAM
- Enhanced Memory and HP would present the 72Mbit DDR ESRAM and PA-RISC at MicroProcessor Forum in 2001
- HP Announcement would drive Ramtron Stock Price Briefly from \$2 to \$30.
- By 2004, Infineon would convince Ramtron to shut-down Enhanced Memory Systems, not wanting to support a lower volume SRAM business
- HP PA-8900 would go to market with a 144Mbit DDR ESRAM-like product from IBM

HP PA-8800 Microprocessor Dual 1GHz PA-RISC Processors Oual 1.5MB L1 Caches 144-bit Wide L2 Cache Interface 4 each 72Mb DDR ESRAM Parts 13 ns Initial Latency 10GB/Second Bandwidth To Be Used In Most HP Workstations and Servers





Enhanced Memory & HP Would Present PA-8800

with ESRAM at Microprocessor Forum 2001

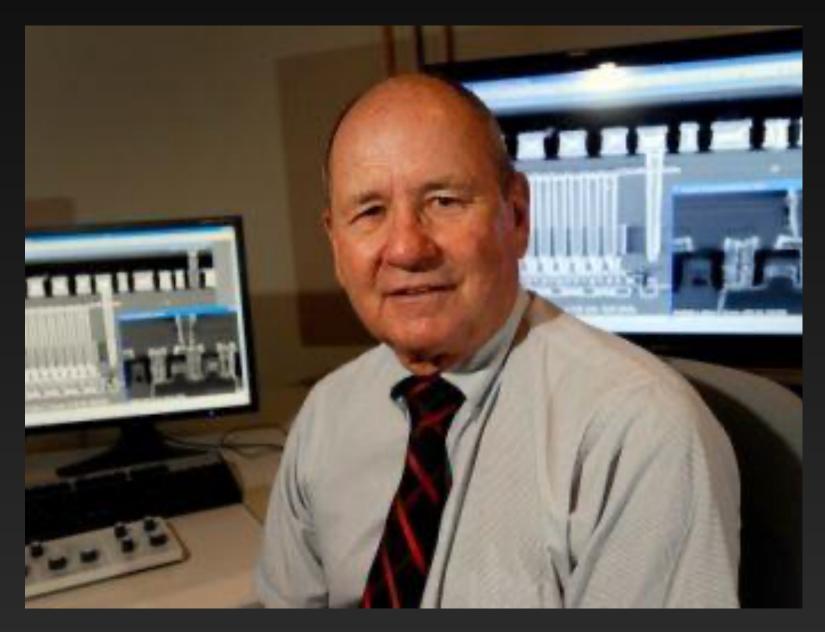






History of the DRAM Integrated Silicon Solutions

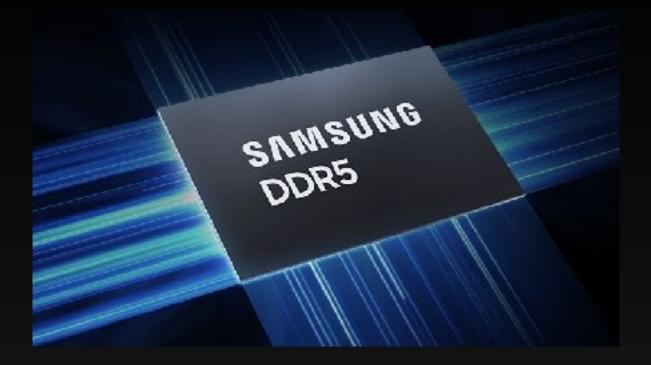
- United Memories continued to design the highest performance DRAM products in Colorado Springs
- United Memories President, Shef Eaton would die in a hang gliding accident
- United Memories would partner with ProMOS Technologies of Taiwan for many years developing DRAMs through 2Gb density
- In addition to standard DRAM, they developed specialty DRAM and embedded DRAM (eDRAM) designs
- One embedded DRAM was a 0.6 volt, 16Mb design with 19.5 ns cycle time
- In 2013, Integrated Silicon Solutions (ISSI), a Specialty DRAM Company, hired many of the UMI design team
- Bob Gower Retired in 2013
- UMI would continued developing DRAM until 2018
- ISSI Continues to develop specialty DRAM products in Colorado Springs today



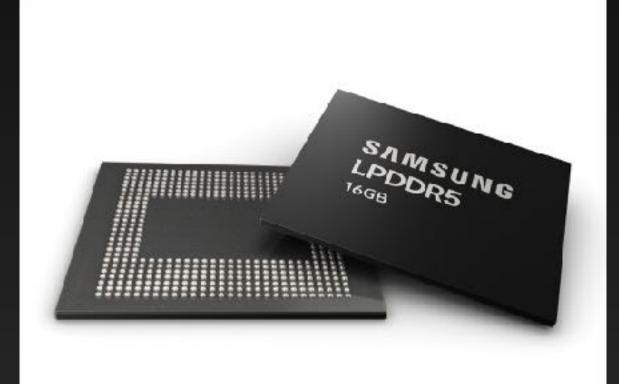
Bob Gower, CEO of United Memories

History of the DRAM DRAM Market Today

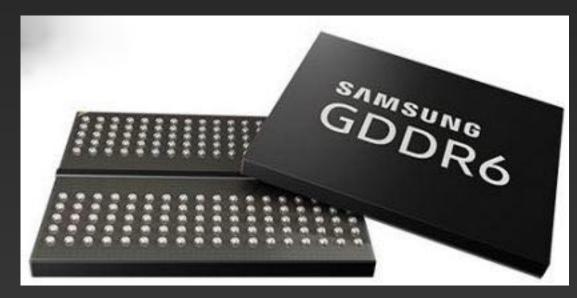
- DRAM Products have been designed on Silicon Mountain for more than 40-years but are not longer manufactured here
- After dominating the DRAM market, Japan was superseded by Korea and Taiwan as leading manufacturers of DRAM
- Micron Technology is only US Manufacturer of DRAM
- Only 3 companies compete for the leading edge DRAM market - Samsung, SK Hynix, and Micron Technology
- DRAM density has reached 16Gb at 10 nm feature size
- The DRAM is now specialized
 - PC & Server Market DDR3, DDR4, and DDR5
 - Mobile Market LPDDR3, LPDDR4, LPDDR5
 - Graphics and GPU Market GDDR6 & HBM



DDR5 DRAM for PC & Servers



LPDDR5 for Smartphones and Tablets



GDDR6 for Graphics and GPUs